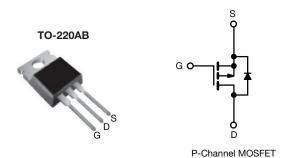


Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	-1	-100			
$R_{DS(on)}(\Omega)$	V _{GS} = -10 V	1.2			
Q _g max. (nC)	8	8.7			
Q _{gs} (nC)	2	2.2			
Q _{gd} (nC)	4.1				
Configuration	Sir	Single			

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9510PbF
Lead (Pb)-free and halogen-free	IRF9510PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	-100	V	
Gate-source voltage			V_{GS}	± 20	7 v	
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C		-4.0		
		T _C = 100 °C	ID	-2.8	Α	
Pulsed drain current ^a			I _{DM}	-16	1	
Linear derating factor				0.29	W/°C	
Single pulse avalanche energy ^b			E _{AS}	200	mJ	
Repetitive avalanche current a			I _{AR}	-4.0	А	
Repetitive avalanche energy ^a			E _{AR}	4.3	mJ	
Maximum power dissipation	$T_C = 1$	25 °C	P _D	43	W	
Peak diode recovery dV/dt ^c			dV/dt	-5.5	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	- °C	
Soldering recommendations (peak temperature) ^d	For	10 s		300		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = -25 V, starting T_J = 25 °C, L = 18 mH, R_q = 25 Ω , I_{AS} = -4.0 A (see fig. 12)
- c. $I_{SD} \le -4.0$ A, $dI/dt \le 75$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 175$ °C
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	3.5		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$			-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	-	- 0.091	-	V/°C	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = \	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$		-	-4.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -100 V, V _{GS} = 0 V		-	-	-100	μA
2010 gate voltage aram ourront	1033		V _{GS} = 0 V, T _J = 150 °C	-	-	-500	μΛ
Drain-source on-state resistance	R _{DS(on)}	$V_{GS} = -10 \text{ V}$	$I_D = -2.4 \text{ A}^{\text{ b}}$	-	-	1.2	Ω
Forward transconductance	9 _{fs}	$V_{DS} = -5$	50 V, I _D = -2.4 A ^b	1.0	-	-	S
Dynamic							
Input capacitance	C_{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	200	-	pF
Output capacitance	C _{oss}			-	94	-	
Reverse transfer capacitance	C _{rss}			-	18	-	
Total gate charge	Qg	V _{GS} = -10 V	I _D = -4.0 A, V _{DS} = -80 V, see fig. 6 and 13 ^b	-	-	8.7	nC
Gate-source charge	Q_{gs}				-	2.2	
Gate-drain charge	Q _{gd}			-	-	4.1	
Turn-on delay time	t _{d(on)}			-	10	-	
Rise time	t _r	V_{DD} = -50 V, I_D = -4.0 A, R_g = 24 Ω , R_D = 11 Ω , see fig. 10 b		-	27	-	- ns
Turn-off delay time	t _{d(off)}			-	15	-	
Fall time	t _f			-	17	-	
Gate input resistance	R_{g}	f = 1 MHz, open drain		1.5	-	7.9	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal source inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	-4.0	^
Pulsed diode forward current ^a	I _{SM}			=	-	-16	A
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = -4.0 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	-5.5	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = -4.0 A, dl/dt = 100 A/μs ^b		-	82	160	ns
Body diode reverse recovery charge	Q _{rr}			-	0.15	0.30	μC
Forward turn-on time	t _{on}	Intrinsic turi	n-on time is negligible (turi	n-on is do	minated b	v Le and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width $\leq 300~\mu s;$ duty cycle $\leq 2~\%$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

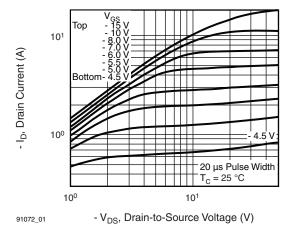


Fig. 1 - Typical Output Characteristics, TC = 25 °C

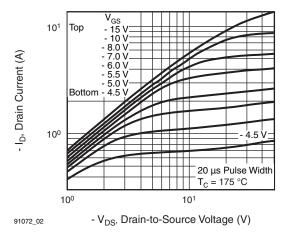


Fig. 2 - Typical Output Characteristics, TC = 175 °C

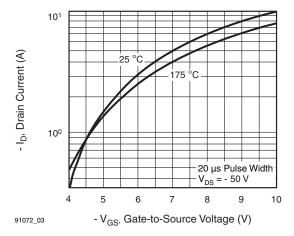


Fig. 3 - Typical Transfer Characteristics

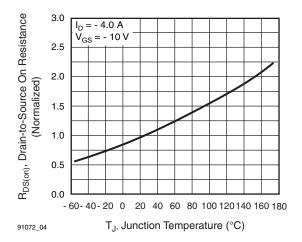


Fig. 4 - Normalized On-Resistance vs. Temperature

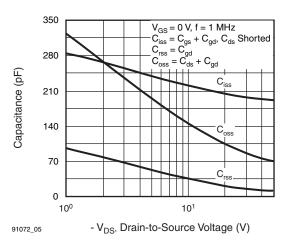


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

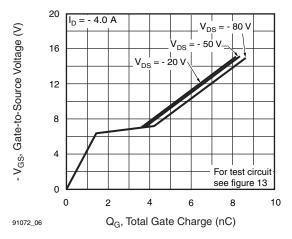


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



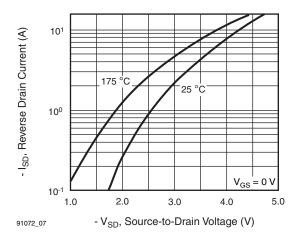


Fig. 7 - Typical Source-Drain Diode Forward Voltage

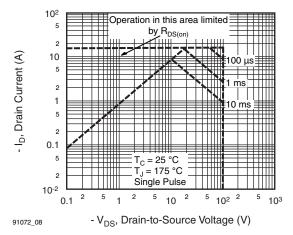


Fig. 8 - Maximum Safe Operating Area

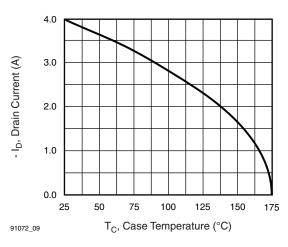


Fig. 9 - Maximum Drain Current vs. Case Temperature

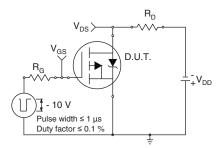


Fig. 10a - Switching Time Test Circuit

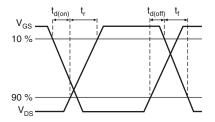


Fig. 10b - Switching Time Waveforms

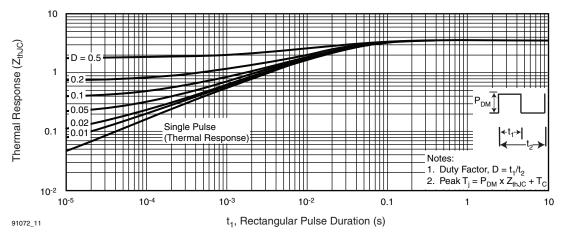


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



Vary t_p to obtain required I_{AS} R_G I_{AS} I

Fig. 12a - Unclamped Inductive Test Circuit

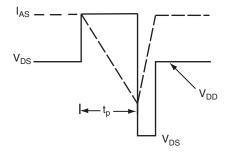


Fig. 12b - Unclamped Inductive Waveforms

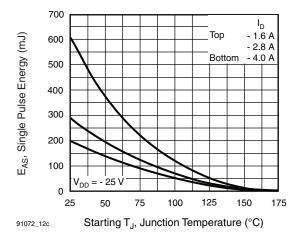


Fig. 12 c- Maximum Avalanche Energy vs. Drain Current

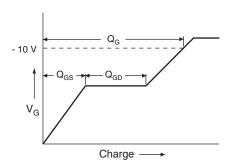


Fig. 13a - Basic Gate Charge Waveform

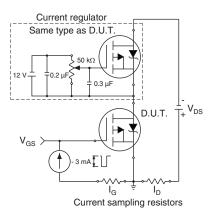
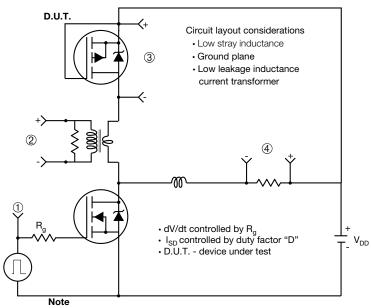


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

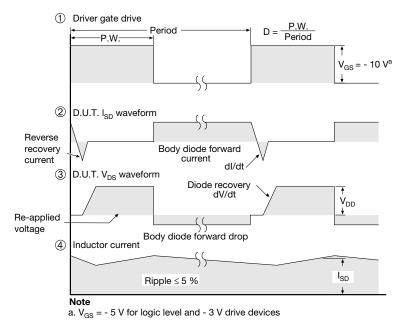


Fig. 14 - For P-Channel

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